RJ45C5 R1U 1.7N4G/Y RL

Weidmüller Interface GmbH & Co. KG
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www.weidmueller.com



The product range encompasses the following designs:
• 90°, lying (horizontal) and 180°, standing (vertical)
• latch up / latch down
• THT, THR or SMD soldering processes
• Wide range of different design types, also with integrated LEDs and shield contact tabs
• Performance category Cat. 3 to Cat. 6
• Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
• Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
• Dielectric strength ≥1500 V AC RMS (2250 V AC peak value) according to IEEE 802.3
• Dielectric strength ≥1500 V AC (peak value) or ≥1500 V DC according to IEC 60603

Properties and advantages:
• Extended temperature range of –40°C to +85°C for maximum performance
• Reinforced gold layer (30µ") for improved corrosion protection
• At least 0.3mm stand-off ensures a perfect soldering result

General ordering data

Version	PCB plug-in connector, RJ45 jacks, THT/THR solder connection, 90°, Latch option: top, LED: Yes, green, yellow, Number of poles: 8, Tape
Order No.	2626090000
Type	RJ45C5 R1U 1.7N4G/Y RL
GTIN (EAN)	4050118630183
Qty.	240 pc(s).
Packaging	Tape

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Technical data

Dimensions and weights

Depth	15.7 mm	Depth (inches)	0.618 inch
Height	13.1 mm	Height (inches)	0.516 inch
Height of lowest version	16.5 mm	Width	16.4 mm
Width (inches)	0.646 inch	Net weight	8.408 g

System specifications

Colour of left LED	green	Colour of right LED	yellow
LED	Yes	Latch option	top
Mounting onto the PCB	THT/THR solder connection	Number of poles	8
Outgoing elbow	90°	Pitch in inches (P)	0.04 inch
Pitch in mm (P)	1.02 mm	Plugging cycles	750
Product family	OMNIMATE Data - RJ45 modular jack	Protection degree	IP20
Shield surface	nickel-plated	Shielding	Yes
Solder pin dimensions	Octagonal	Solder pin length (l)	1.7 mm
Soldering process	Reflow soldering, Manual soldering, Wave soldering	Tolerance of solder pin position	± 0.1 mm
Type of connection	Solder connection		

Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC
Insulation strength	≥ 500 MΩ	PoE / PoE+	conforming to IEEE 802.3at
Rated current	1.5 A	Rated voltage	125 V

Material data

Insulating material	PA 9T	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	II
Insulation strength	≥ 500 MΩ	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact base material	Phosphor bronze alloy
Contact surface	Gold over nickel	Storage temperature, min.	-40 °C
Storage temperature, max.	85 °C	Operating temperature, min.	-40 °C
Operating temperature, max.	85 °C		

Packing

Packaging	Tape	VPE length	359 mm
VPE width	354 mm	VPE height	128 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27460201

Approvals

ROHS	Conform

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Technical data

Downloads

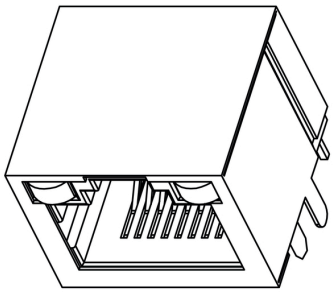
Approval/Certificate/Document of Conformity	Certificate of Compliance
Catalogues	Catalogues in PDF-format

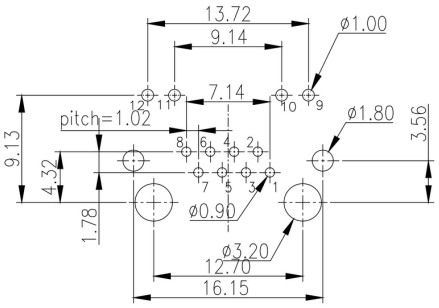
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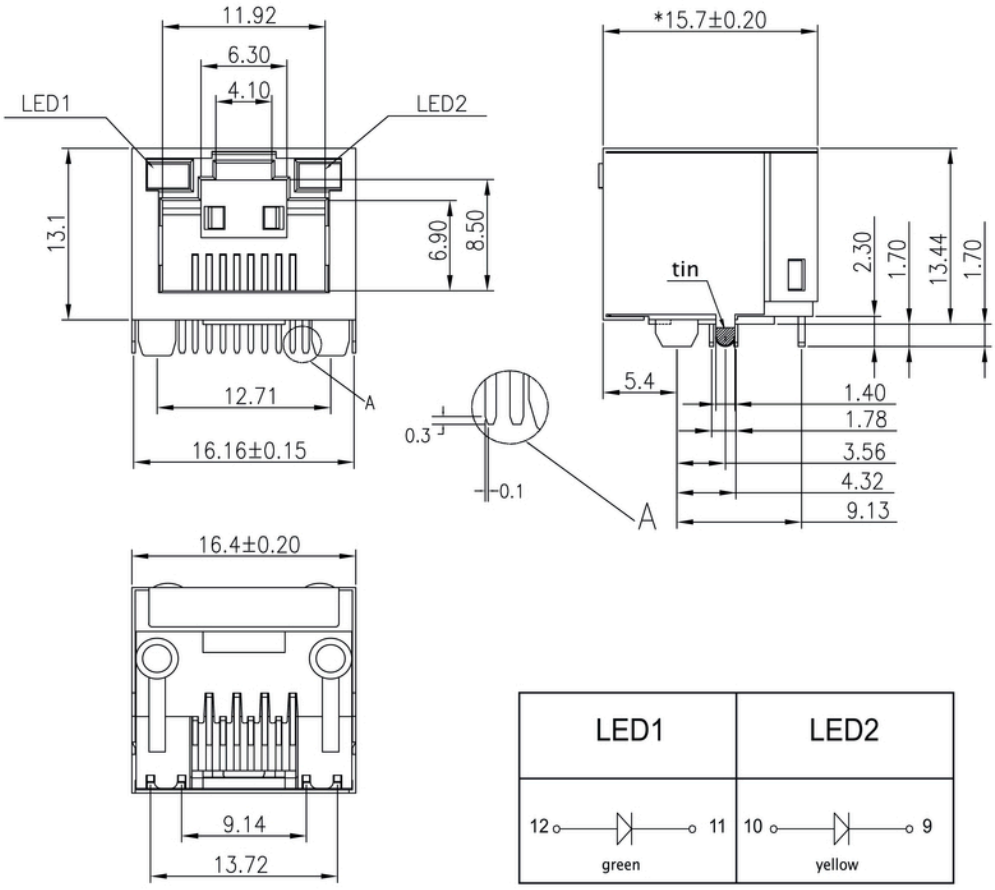
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Drawings







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Drawings

RJ45 G1 R 1 U 3.2 E 4 GY/GY TY RJ45G1 R1U 3.2E4GY/GY TY

Packaging	**TY**	**T**ray in box (manual assembly)
	RL	Tape on **R**eel (automated assembly)
LED	**Y/G**	**Y**ellow/**G**reen
	G/Y	**G**reen/**Y**ellow (standard)
	GY/GY	**G**reen-**Y**ellow/**G**reen-**Y**ellow
	O/G	**O**range/**G**reen
	R/O	**R**ed/**O**range
	...	... (further combinations possible)
	N	without LED
Contact surface thickness	**4**	1 = 3µ", 2 = 6µ", 3 = 15µ", **4 = 30µ"**, 5 = 50µ"
EMI tabs (ground fingers)	**E**	**E** = with EMI tabs
	N	**N** = without EMI tabs
Solder Pin length	**3.2**	3.2 mm
	1.6	1.6 mm
	D	SM**D**
Direction, latch style	**U**	Horizontal (90°, side entry), latch **u**p
	D	Horizontal (90°, side entry), latch **d**own
	V	**V**ertical (180°, top entry)
	Y	Diagonal (45°), latch up
Number of Ports	**1**	1 Port
	12; 14; ...	multi ports side by side, Multiport
	21; 41; ...	multi ports about each other, Multilevel
Assembly on PCB	**R**	Through Hole **R**eflow - THR Soldering process: Wave or Reflow soldering
	S	**S**urface Mount Technology - **S**MT Soldering process: Reflow soldering
	T	Through Hole Technology - TH**T** Soldering process: Wave
Performance Category	**C5**	**C**ategory **5**
	C6	**C**ategory **6**
	C6A	**C**ategory **6A**
	C5e	**C**ategory **5e**
	M	10/100 Mbit
	G1	10/100/1000 Mbit
	G10	10 Gbit
	U	**U**nshielded
	MP	10/100 Mbit with **P**OE
	MP+	10/100 Mbit with **P**OE+

Legend

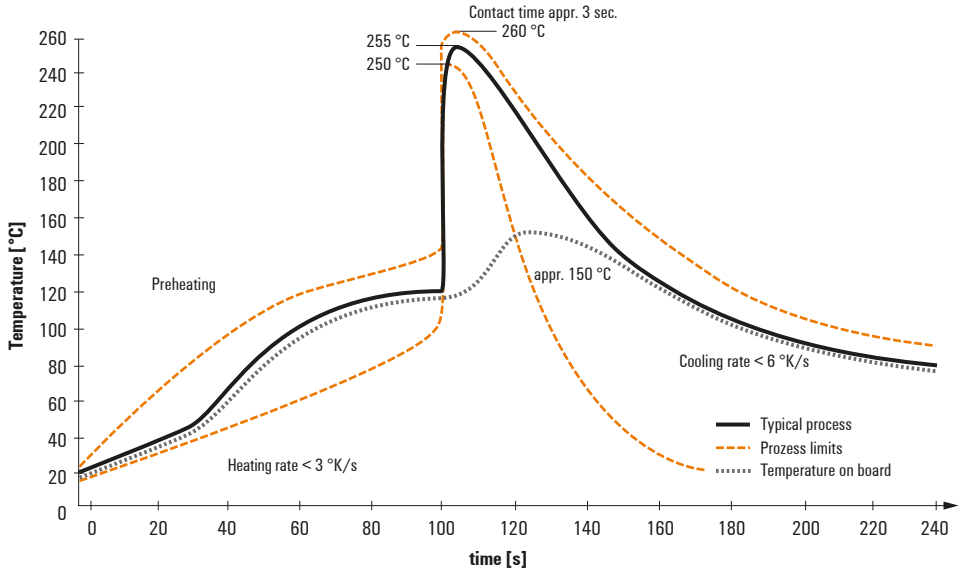
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Wave Solder Profile

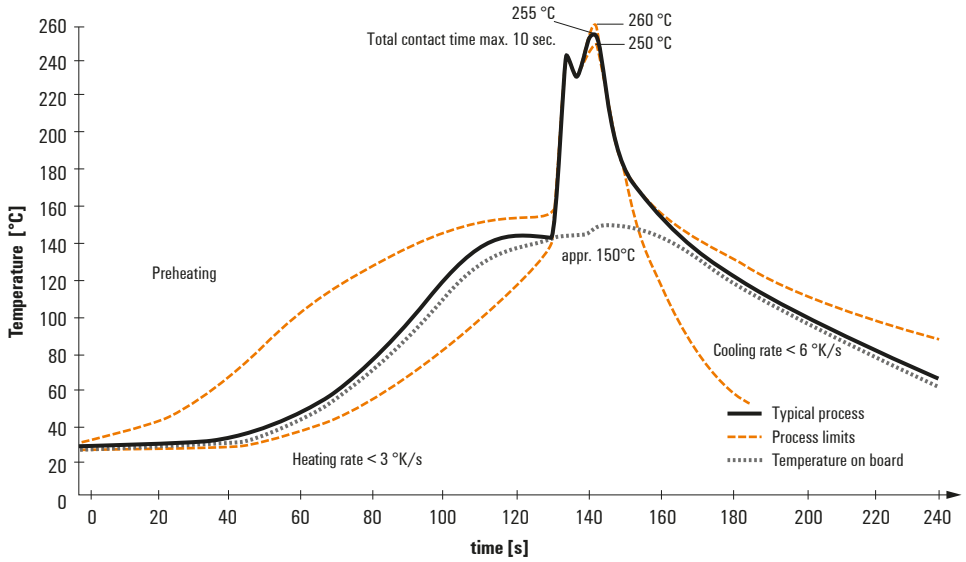
Recommended wave solderding profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

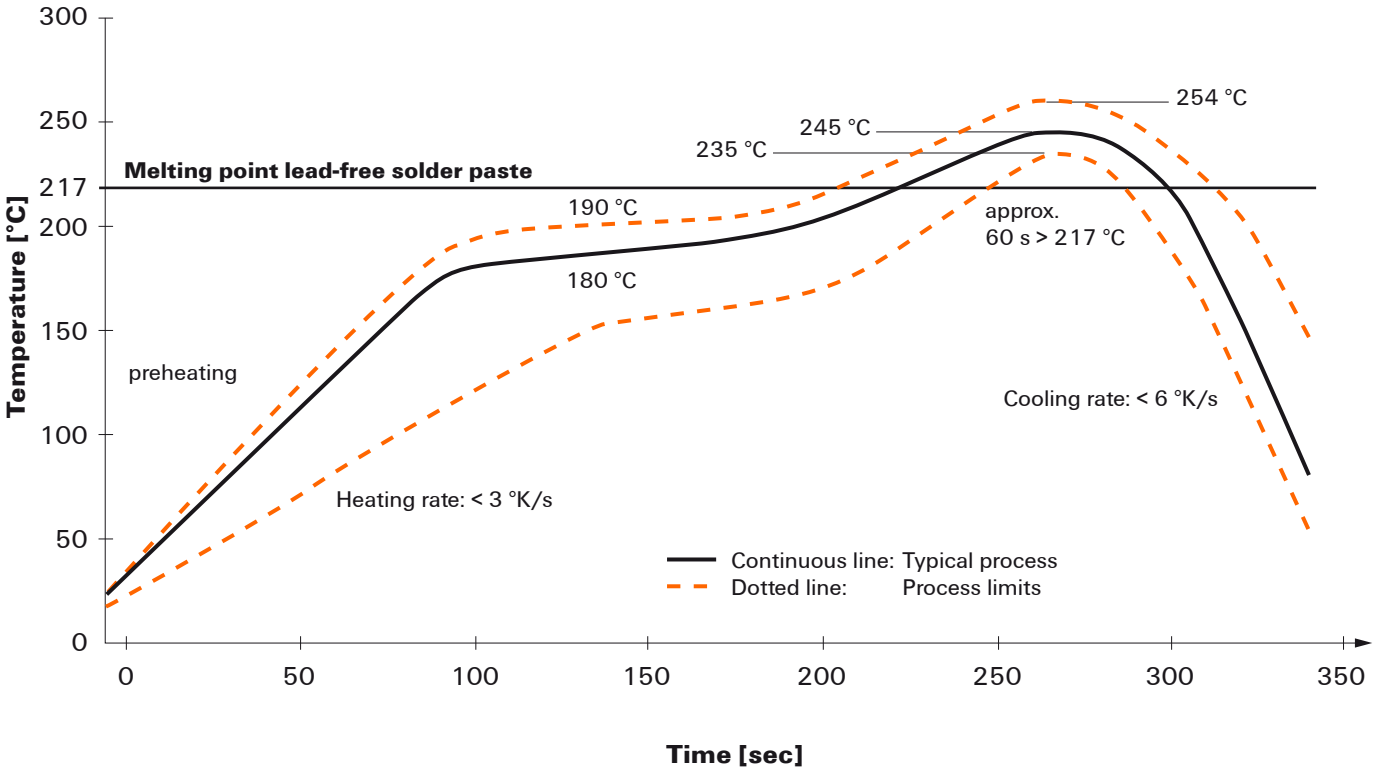
The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Reflow Solder Profile

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.

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